ABSTRACT OF THE DISCLOSURE

A power supply layout for an integrated circuit comprises a plurality of power pads, a plurality of ground pads, a plurality of first-type conductive wires directly connected to the power pad, a plurality of second-type conductive wires directly connected to the ground pad, and a core circuit electrically connected to the first-type and the second-type conductive wires for acquiring the operational power. The integrated circuit is made of a plurality of metal layers, wherein the first-type conductive wire and the second-type conductive wire are positioned at different metal layers. The power pad is positioned at the same metal layer as the first-type conductive wire, while the ground pad is positioned at the same metal layer as the second-type conductive wire.